

Silicon-free Thermal Conductive Pad

TP1000-H60-SF is a Silicon-free Thermal Conductive Pad, which is a high thermal conductivity, high strength, and flame-retardant interface thermal conductive material specially designed and developed for silicone-sensitive applications. It can meet a variety of application scenarios such as high compression, multiple rework, tear resistance, and high-frequency vibration impact.



Features & Benefits

- Thermal conductivity: 10.0 W/(m·K)
- No silicone oil precipitation or siloxane volatilization
- Good mechanical properties
- Weak viscosity
- High insulation
- Good durability
- High compression

Typical Applications

- Fiber optic module
- Medical equipment
- Hard disk drive
- Optical precision equipment
- High-end industrial control equipment
- Silicone-sensitive component/equipment/product
- Automotive sensor/control module

Typical Properties		
Properties	Attribute	Test Method
Color	Grayish Green	Visual
Thickness (mm)	0.5~3.0	ASTM D374
Density (g/cc)	3.3	ASTM D792
Hardness (Shore 00)	60	ASTM D2240
Weight Loss (%)	≤1.0	Filter paper adsorption @ 25% compression/125°C/48h
Usage Temperature (°C)	-40~125	/
Flammability	V-0	UL 94
Shelf Life (months)	12	Temperature <40°C avoid extrusion and exposure to the sun
Electrical		
Breakdown Voltage (kV/mm)	≥6.0	ASTM D149
Dielectric Constant	5.8	ASTM D150
Volume Resistivity (Ω·cm)	10 ¹⁰	ASTM D257
Thermal		
Thermal Conductivity (W/(m·K))	10.0	ISO 22007-2

